



DFN6 5x6, 1.27P CASE 506DV ISSUE O

DETAIL A
ALTERNATE TERMINAL

CONSTRUCTIONS

ALTERNATE A-2

ALTERNATE CONSTRUCTIONS

ALTERNATE A-1

**DATE 12 OCT 2016** 

## NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25 MM FROM THE TERMINAL TIP.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
- 5. FOR DEVICE OPN CONTAINING W OPTION, DETAIL B ALTERNATE B-1 AND DETAIL A ALTERNATE A-1 CONSTRUCTIONS ARE NOT APPLICABLE.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.80	0.90	1.00	
A1			0.05	
A3	0.20 REF			
b	0.30	0.40	0.50	
D	4.90	5.00	5.10	
D2	4.10	4.20	4.30	
Е	5.90	6.00	6.10	
E2	1.75	1.85	1.95	
е	1.27 BSC			
e2	3.81 BSC			
K	0.25			
Ĺ	0.45	0.55	0.65	

## TOP VIEW EXPOSED CU MOLD CMPD O.10 C DETAIL A A3 A1 A1 ALTERNATE B-1 ALTERNATE B-2 NOTE 4 SIDE VIEW C PLANE A3 A1 ALTERNATE B-1 ALTERNATE B-1 ALTERNATE B-1 ALTERNATE B-1 ALTERNATE B-1 ALTERNATE B-1 ALTERNATE B-1

## 10X **b** 0.10 C A B -6X L RECOMMENDED 0.05 C NOTE 3 SOLDERING FOOTPRINT\* **DETAIL A** 5.30 4.41 E2 6X 0.60 1.27 PITCH 1 95 D2 **BOTTOM VIEW** 6.30 0.20 0.75 PACKAGE OUTLINE

## GENERIC MARKING DIAGRAM\*



A = Assembly Location

LL = Wafer Lot

YY = Year

WW = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.

\*For additional information on our Pb–Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**DIMENSIONS: MILLIMETERS** 

PITCH

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